



## Material Content Data Sheet



<b>Sales Product Name</b>		BFP 193W H6327		<b>Issued</b>		20. July 2018			
<b>MA#</b>		MA001303734							
<b>Package</b>		PG-SOT343-4-1		<b>Weight*</b>		6.74 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	noble metal	gold	7440-57-5	0.002	0.03		268		
	non noble metal	tin	7440-31-5	0.000	0.01		69		
	inorganic material	silicon	7440-21-3	0.016	0.23	0.27	2312	2649	
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100		
	non noble metal	titanium	7440-32-6	0.003	0.05		499		
	non noble metal	chromium	7440-47-3	0.010	0.15		1497		
	non noble metal	copper	7440-50-8	3.347	49.69	49.90	496967	499063	
wire	noble metal	gold	7440-57-5	0.013	0.19	0.19	1912	1912	
encapsulation	organic material	carbon black	1333-86-4	0.031	0.46		4573		
	plastics	epoxy resin	-	0.662	9.83		98322		
	inorganic material	silicondioxide	60676-86-0	2.387	35.44	45.73	354417	457312	
leadfinish	non noble metal	tin	7440-31-5	0.199	2.96	2.96	29580	29580	
plating	noble metal	silver	7440-22-4	0.064	0.95	0.95	9484	9484	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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